0.001%(Typ)



# Sound Processor with Built-in 3-band Equalizer

### BD37532FV

#### **General Description**

BD37532FV is a sound processor with built-in 3-band equalizer for car audio. A stereo input selector is available that functions to switch single end input and ground isolation input, input-gain control, main volume, loudness, 5ch fader volume and LPF for subwoofer. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and constructs a high quality car audio system.

#### **Features**

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, loudness by using advanced switch circuit
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces volume switching noise for portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer and loudness filter. It is possible to freely control Q, Gv, fo of 3-band equalizer and fc of LPF, Gv of loudness by I<sup>2</sup>C BUS control.
- A gain adjustment quantity of ±20dB with a 1 dB step gain adjustment is possible for bass, middle and treble.
- Equipped with terminals for subwoofer outputs. Also, the audio signal outputs of the front, rear and subwoofer can be chosen using the I<sup>2</sup>C BUS control.
- Energy-saving design resulting in low current consumption is achieved utilizing the BiCMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input pins and output pins are organized and separately laid out in such a way that it simplifies the pattern layout of the PCB and decreases the board dimensions.
- It is possible to control I<sup>2</sup>C BUS with 3.3V / 5V.

### **Applications**

It is optimal for car audio systems. It can also be used for audio equipments like mini Compo, micro Compo, TV etc.

### **Key Specifications**

Power Supply Voltage Range: 7.0V to 9.5VCircuit Current (No Signal): 38mA(Typ)

Total Harmonic Distortion 1: (FRONT,REAR)

Total Harmonic Distortion 2:

(SUBWOOFER) 0.002%(Typ)

Maximum Input Voltage: 2.3Vrms(Typ)

Crosstalk Between Selectors: -100dB(Typ)

Volume Control Range: +15dB to -79dB

Output Noise Voltage 1:

(FRONT,REAR) 3.8 $\mu$ Vrms(Typ)

Output Noise Voltage 2:

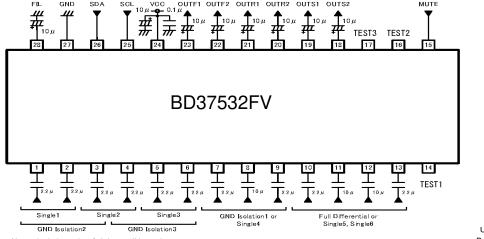
(SUBWOOFER) 4.8μVrms(Typ)
Residual Output Noise Voltage: 1.8μVrms(Typ)
Operating Temperature Range: -40°C to +85°C

#### Package

 $W(Typ) \times D(Typ) \times H(Max)$ 



## **Typical Application Circuit**

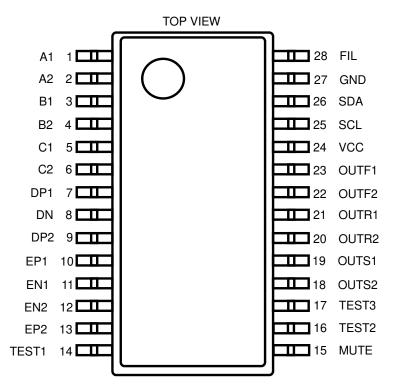


About single input 1 to 3, it is possible to change from single input to GND Isolation input 2,3.

About GND Isolation1 and Full Differential, it is possible to change from differential input to single input 4 to 6.

Unit R : [Ω] C : [F]

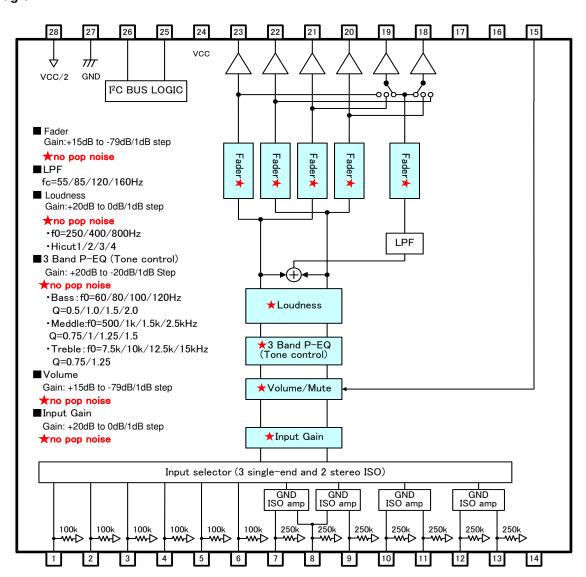
# **Pin Configuration**



**Pin Descriptions** 

Description	Ulia				
Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	15	MUTE	External compulsory mute terminal
2	A2	A input terminal of 2ch	16	TEST2	Test pin
3	B1	B input terminal of 1ch	17	TEST3	Test pin
4	B2	B input terminal of 2ch	18	OUTS2	Subwoofer output terminal of 2ch
5	C1	C input terminal of 1ch	19	OUTS1	Subwoofer output terminal of 1ch
6	C2	C input terminal of 2ch	20	OUTR2	Rear output terminal of 2ch
7	DP1	D positive input terminal of 1ch	21	OUTR1	Rear output terminal of 1ch
8	DN	D negative input terminal	22	OUTF2	Front output terminal of 2ch
9	DP2	D positive input terminal of 2ch	23	OUTF1	Front output terminal of 1ch
10	EP1	E positive input terminal of 1ch	24	VCC	Power supply terminal
11	EN1	E negative input terminal of 1ch	25	SCL	I <sup>2</sup> C Communication clock terminal
12	EN2	E negative input terminal of 2ch	26	SDA	I <sup>2</sup> C Communication data terminal
13	EP2	E positive input terminal of 2ch	27	GND	GND terminal
14	TEST1	Test pin	28	FIL	VCC/2 terminal

# **Block Diagram**



# **Absolute Maximum Ratings** (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power supply Voltage	Vcc	10.0	V
Input voltage	Vin	V <sub>CC</sub> +0.3 to GND-0.3	V
Power Dissipation	Pd	1.06 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on ROHM Standard board(70x70x1.6 (mm³), derate by 8.5mW/°C for Ta=25°C or more.

Thermal resistance 6ja = 117.6(°C/W)

Material: A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

# **Recommended Operating Conditions**

Parameter	Symbol	Limit	Unit
Power Supply Voltage	V <sub>CC</sub>	7.0 to 9.5	V
Temperature	Topr	-40 to +85	°C

### **Electrical Characteristics**

(Unless otherwise noted, Ta=25°C, Vcc=8.5V, f=1kHz, V $_{IN}$ =1Vrms, Rg=600 $\Omega$ , RL=10k $\Omega$ , A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, Fader 0dB)

	Tr, volume odb, tone control od	D, Loudiness	oub, Li i	Limit	iei oub)		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current	ΙQ	-	38	48	mA	No signal
	Voltage Gain	Gv	-1.5	0	+1.5	dB	Gv=20log(Vout/Vin)
	Channel Balance	CB	-1.5	0	+1.5	dB	$CB = G_{V1} - G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz
AL	Output Noise Voltage 1 (FRONT,REAR) *	V <sub>NO1</sub>	-	3.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GENERAL	Output Noise Voltage 2 (SUBWOOFER) *	V <sub>NO2</sub>	ı	4.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GE	Residual Output Noise Voltage	V <sub>NOR</sub>	-	1.8	10	μVrms	Fader = $-\infty$ dB Rg = $0\Omega$ BW = IHF-A
	Crosstalk Between Channels*	СТС	-	-100	-90	dB	$Rg = 0\Omega$ $CTC=20log(V_{OUT}/V_{IN})$ $BW = IHF-A$
	Ripple Rejection	RR	1	-70	-40	dB	$ \begin{array}{l} f=1kHz \\ V_{RR}=100mVrms \\ RR=20log(V_{CC}\ IN/V_{OUT}) \end{array} $
	Input Impedance (A, B, C)	R <sub>IN_S</sub>	70	100	130	kΩ	
	Input Impedance (D, E)	R <sub>IN_D</sub>	175	250	325	kΩ	
OR	Maximum Input Voltage	V <sub>IM</sub>	2.1	2.3	_	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1%
l E		- 1101					BW=400Hz-30KHz
T SELECTOR	Crosstalk Between Selectors *	CTS	-	-100	-90	dB	$Rg = 0\Omega$ $CTS=20log(V_{OUT}/V_{IN})$ BW = IHF-A
TUPUT	Common Mode Rejection Ratio * (D, E)	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V <sub>IN</sub> /V <sub>OUT</sub> ) BW = IHF-A,[*X···D,E]

# **Electrical Characteristics – continued**

ectrical	Characteristics – continue						
BLOCK	Parameter	Symbol		Limit		Unit	Conditions
BL		,,,,,,	Min	Тур	Max		
GAIN	Minimum Input Gain	Gіn_міn	-2	0	+2	dB	Input gain 0dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )
INPUT	Maximum Input Gain	G <sub>IN_MAX</sub>	+18	+20	+22	dB	Input Gain +20dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	G <sub>IN_ERR</sub>	-2	0	+2	dB	Gain=+20dB to +1dB
MUTE	Mute Attenuation *	G <sub>мите</sub>	-	-105	-85	dB	Mute ON G <sub>MUTE</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
Е	Maximum Gain	Gv_max	13	15	17	dB	Volume = 15dB V <sub>IN</sub> =100mVrms Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
VOLUME	Maximum Attenuation *	Gv_min	-	-100	-85	dB	Volume = -∞dB Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
	Attenuation Set Error 1	G <sub>V_ERR1</sub>	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB
0	Maximum Boost Gain	G <sub>B_BST</sub>	18	20	22	dB	Gain=+20dB f=100Hz V <sub>IN</sub> =100mVrms GB=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
BASS	Maximum Cut Gain	<b>G</b> в_сит	-22	-20	-18	dB	Gain=-20dB f=100Hz V <sub>IN</sub> =2Vrms GB=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	G <sub>B_ERR</sub>	-2	0	+2	dB	Gain=+20dB to -20dB f=100Hz
)LE	Maximum Boost Gain	<b>G</b> м_вѕт	18	20	22	dB	Gain=+20dB f=1KHz V <sub>IN</sub> =100mVrms GM=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
MIDDLE	Maximum Cut Gain	<b>G</b> м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V <sub>IN</sub> =2Vrms GM=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	G <sub>M_ERR</sub>	-2	0	+2	dB	Gain=+20dB to -20dB f=1kHz
Щ	Maximum Boost Gain	Gt_bst	18	20	22	dB	Gain=+20dB f=10kHz V <sub>IN</sub> =100mVrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
TREBL	Maximum Cut Gain	<b>G</b> т_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V <sub>IN</sub> =2Vrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	GT_ERR	-2	0	+2	dB	Gain=+20dB to -20dB f=10kHz
ΞR	Maximum Boost Gain	G <sub>F_BST</sub>	13	15	17	dB	
FADER / SUBWOOFER	Maximum Attenuation *	GF_MIN	-	-100	-90	dB	Fader = -∞dB GF=20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
	Gain Set Error	G <sub>F_ERR</sub>	-2	0	+2	dB	Gain=+15dB to +1dB
S	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=-1dB to -15dB
ıς	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G <sub>F_ERR3</sub>	-4	0	+4	dB	ATT=-48dB to -79dB
FA	Output Impedance	Rоит	-	-	50	Ω	V <sub>IN</sub> =100mVrms
	Maximum Output Voltage	V <sub>OM</sub>	2	2.2	_	Vrms	THD+N=1% BW=400Hz-30KHz
VESS	Maximum Gain	GL_MAX	17	20	23	dB	Gain 20dB V <sub>IN</sub> =100mVrms GL=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
LOUDNESS	Gain Set Error	G <sub>L_ERR</sub>	-2	0	+2	dB	GAIN=+20dB to +1dB

VP-9690A (Average value detection, effective value display) filter by Matsushita Communication is used for \* measurement. Phase between input / output is same.

# **Typical Performance Curves**

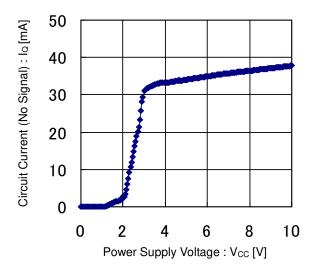


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

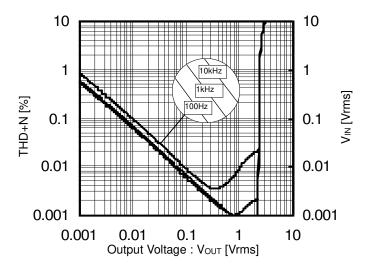


Figure 2. Total Harmonic Distortion vs Output Voltage

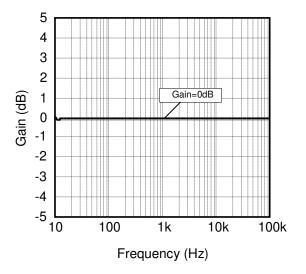


Figure 3. Gain vs Frequency

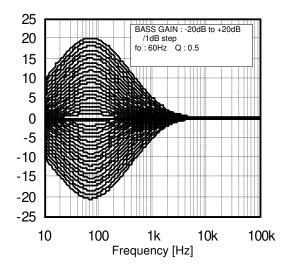


Figure 4. Bass Gain vs Frequency

Gain[dB]

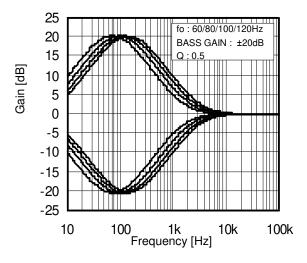


Figure 5. Bass fo vs Frequency

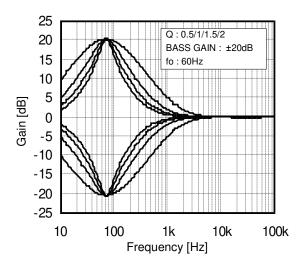


Figure 6. Bass Q vs Frequency

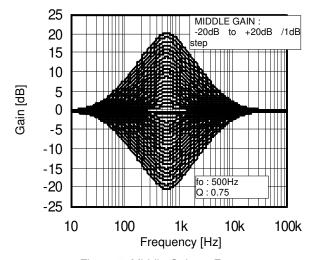


Figure 7. Middle Gain vs Frequency

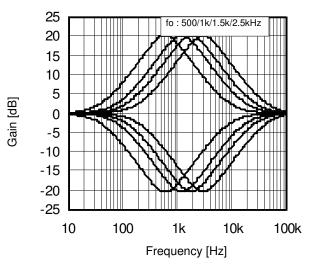


Figure 8. Middle fo vs Frequency

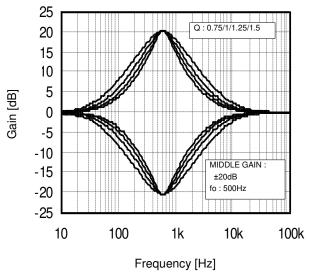


Figure 9. Middle Q vs Frequency

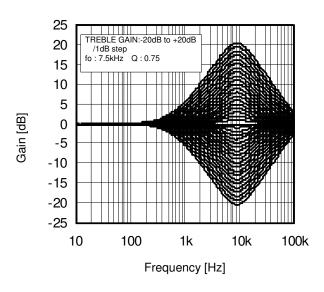


Figure 10. Treble Gain vs Frequency

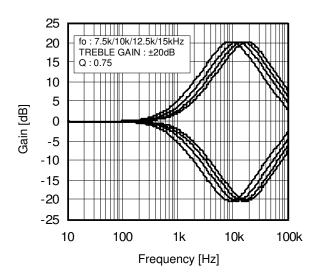


Figure 11. Treble fo vs Frequency

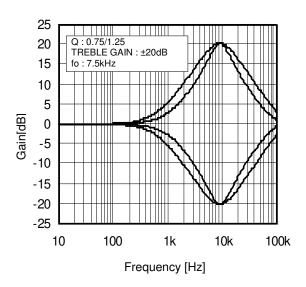


Figure 12. Treble Q vs Frequency

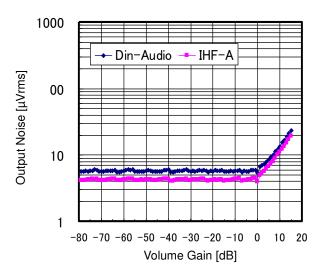


Figure 13. Output Noise vs Volume Gain

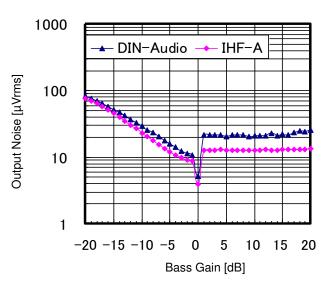


Figure 14. Output Noise vs Bass Gain

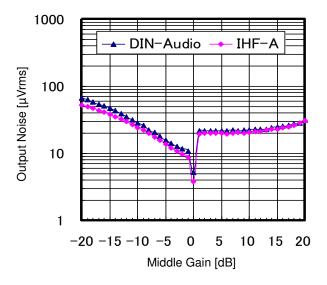


Figure 15. Output Noise vs Middle Gain

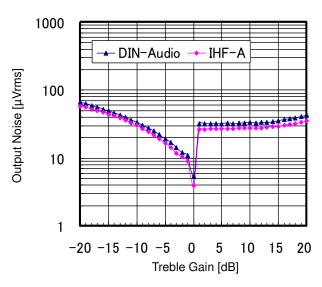
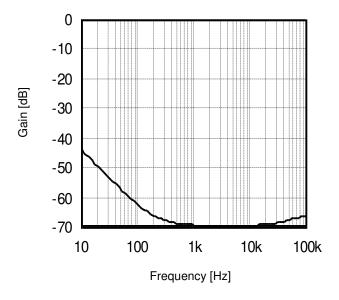


Figure 16. Output Noise vs Treble Gain



2.0
1.5
1.0
0.5
0.0
100 1000 10000 100000

RLOAD [ohm]

2.5

Figure 17. CMRR vs Frequency

Figure 18. Output Voltage vs R<sub>LOAD</sub>

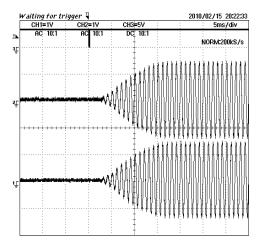


Figure 19. Advanced Switch 1

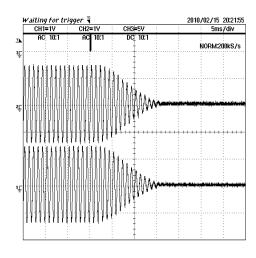


Figure 20. Advanced Switch 2

# **Timing Chart**

## **CONTROL SIGNAL SPECIFICATION**

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

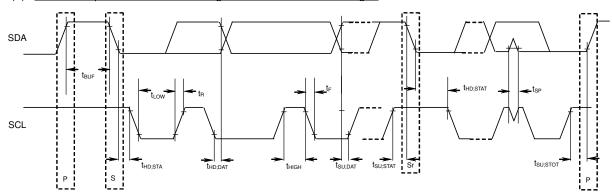


Figure 21. Definition of Timing on the I<sup>2</sup>C-bus

Table 1 Characteristics of the SDA and SCL bus lines for I<sup>2</sup>C-bus devices (Unless specified particularly, Ta=25°C, Vcc=8.5V)

	Parameter	Cumbal	Fast-mod	le I <sup>2</sup> C-bus	Unit
	Parameter	Symbol	Min	Max	Unit
1	SCL clock frequency	f <sub>SCL</sub>	0	400	kHz
2	Bus free time between a STOP and START condition	<b>t</b> BUF	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock	<b>+</b>	0.0		
3	pulse is generated	thd;sta	0.6	1	μS
4	LOW period of the SCL clock	$t_{LOW}$	1.3	-	μS
5	HIGH period of the SCL clock	tніgн	0.6	ı	μS
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS
7	Data hold time:	t <sub>HD;DAT</sub>	0.06 <sup>(Note)</sup>	-	μS
8	Data set-up time	tsu;dat	120	1	ns
9	Set-up time for STOP condition	tsu;sто	0.6		μS

All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) The device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

About 7 ( $t_{\text{HD;DAT}}$ ), 8( $t_{\text{SU;DAT}}$ ), make the setup in which the margin is fully in .

Table 2 Characteristics of the SDA and SCL I/O stages for I<sup>2</sup>C-bus devices

	Parameter	Cumbal	Fast-mode	Unit	
	Parameter	Symbol	Min	Max	Offic
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	V <sub>IH</sub>	2.3	5	٧
12	Pulse width of spikes which must be suppressed by the input filter.	tsp	0	50	ns
13	LOW level output voltage: at 3mA sink current	V <sub>OL1</sub>	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	l <sub>l</sub>	-10	+10	μA

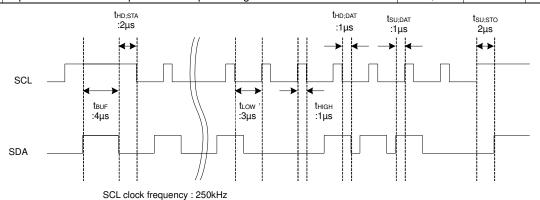


Figure 22. A Command Timing Example in the I<sup>2</sup>C Data Transmission

## (2) <u>I<sup>2</sup>C BUS FORMAT</u>

	MSB	LSB		MSB	LSB	}	MSB		LSB					
S	Slave	Address	Α	Select	Address	Α		Data		Α	Р			
1bit	8bit		1bit		8bit	1bit		8bit		1bit	1bit			
	S		= Sta	= Start conditions (Recognition of start bit)										
	Slav	e Address	= Re	= Recognition of slave address. 7 bits in upper order are voluntary										
			The	The least significant bit is "L" for write mode.										
	Α		= ACKNOWLEDGE bit (Recognition of acknowledgement)											
	Sele	ct Address	= Select address for volume, bass and treble.											
	Data	l	= Data on every volume and tone.											
	P = Stop condition (Recognition of stop bit)													

# (3) I<sup>2</sup>C BUS Interface Protocol

(a)	Basic	form

<u>(u)</u> -	Jacio Ioiiii								
S	Slave Addre	ess	Α	Select Add	Α	Data	Α	Р	
	MSB LSB		1	MSB	LSB	M	1SB	LSB	

(b) Automatic increment (Select Address increases (+1) according to the number of data.

S	Slave Address	Α	Select Address	Α	Data1	Α	Data2	Α		DataN	Α	Р
- 1	MSB LSB	MS	SB LSB	MS	B LSB	N	ISB LSB		ı	MSB L	.SB	

(Example) ①Data1 shall be set as data of address specified by Select Address.

- ②Data2 shall be set as data of address specified by Select Address +1.
- ③DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration unavailable for transmission (In this case, only Select Address1 is set.

3	3 3	lave Address A Se		Select A	elect Address1		Dat	ta	Α	Select	lect Address 2		Α	Dat	ta A	<b>\</b>	Р
	MSI	ISB LSB MSB		LSB	M	MSB LSB MSB			MSB		LSB	M	SB	LSB			
	(Note) If any data is transmitted as Select Address 2 next to data, it is recognized																
		as data, not as Select Address 2.															

## (4) Slave Address

MSB							LSB	_
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

## (5) Select Address & Data

Items	Select Address	MSB			Da	ata			LSB
items	(hex)	D7	D6	D5	D4	D3	D2	D1	D0
Initial setup 1	01	Advanced switch ON/OFF	0	of Input Ga	switch time ain/Volume r/Loudness	0	1		switch time /lute
Initial setup 2	02	LPF Phase	0		er Output lect	0	Su	bwoofer LPI	= fc
Initial setup 3	03	0	0	0	Loudness fo 0 0			1	
Input Selector	05	Full-diff Type	0	0	Input selector				
Input gain	06	Mute ON/OFF	0	0 Input Gain					
Volume gain	20			,	Volume Gain	/ Attenuatio	n		
Fader 1ch Front	28				Fader Gain	/ Attenuation	1		
Fader 2ch Front	29				Fader Gain	/ Attenuation	1		
Fader 1ch Rear	2A		Fader Gain / Attenuation						
Fader 2ch Rear	2B				Fader Gain	/ Attenuation	1		
Fader Subwoofer	2C				Fader Gain	/ Attenuation	1		
Test Mode	30	1	1	1	1	1	1	1	1
Bass setup	41	0	0	Bas	s fo	0	0	Bas	ss Q
Middle setup	44	0	0	Midd	lle fo	0	0	Midd	dle Q
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain		
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain				
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain				
Loudness Gain	75	0	Loudn	ess Hicut		L	oudness Ga	in	
System Reset	FE	1	0	0	0	0	0	0	1

Advanced switch

### Note

- 1. The Advanced Switch works in the latch part while changing from one function to another..
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

- 3. Advanced Switch is not used for the functions of input selector and subwoofer output select etc. Please turn on MUTE when changing the settings of this side of the set.
- 4. When using Mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

Select address 01 (hex)

	MSB	Ad	dvance	ed swit	ch tim	e of M	ute	LSB
Time	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	A -l		A -l				0	0
1.0msec	Advanced	0		switch time		4	0	1
1.4msec	Switch ON/OFF	U		ain/Volume er/Loudness	0	ı	1	0
3.2msec	OIN/OI I		Torre/T auc	ei/Loudiless			1	1

Time	MSB	Advanced switch time of Input gain/Volume/Tone/Fader/Loudness								
	D7	D6	D5	D4	D3	D2	D1	D0		
4.7 msec	A alv (a) a a a al		0	0						
7.1 msec	Advanced Switch	0	0	1	1 ^	4	Advanced switch			
11.2 msec	ON/OFF		1	0	] "	'	of Mute			
14.4 msec	ON/OFF		1	1						

Mode	MSB		Advanced switch ON/OFF LSE						
IVIOGE	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0		switch time ain/Volume	0	1		ed switch	
ON	1			r/Loudness			Time o	of Mute	

Select address 02(hex)

OCICOL addices of (TICK								
fo	MSB		Subwoofer LPF fc					
fc	D7	D6	D5	D4	D3	D2	D1	D0
OFF						0	0	0
55Hz						0	0	1
85Hz	LDE Dhasa	0	Subwoof	er Output		0	1	0
120Hz	LPF Phase	U	Se	lect	0	0	1	1
160Hz						1	0	0
Prohibition							Other setting	

Mode	MSB		Subwo	oofer C	Dutput	Select	t	LSB
ivioue	D7	D6	D5	D4	D3	D2	D1	D0
LPF			0	0				
Front	I DE DI	•	0	1		Subwoofer LPF fc	- ,	
Rear	LPF Phase	0	1	0	Ü		- IC	
Prohibition			1	1				

Phase	MSB		LPF Phase							
Filase	D7	D6	D5	D4	D3	D2	D1	D0		
0°	0	0	Subwoot	fer output	0	Q <sub>11</sub>	bwoofor I Di	= fo		
180°	1		se	lect	0	Su	Subwoofer LPF fc			

Select address 03(hex)

fO	MSB			Loudr	ness fo	)		LSB
TU	D7	D6	D5	D4	D3	D2	D1	D0
250Hz				0	0			
400Hz	0	^	0	0	1	0	_	4
800Hz	U	U	U	1	0	U	U	1
Prohibition				1	1			

	Initial	condition

Select address 05(hex)

Mode		•	MSB		Ir	iput S	Select	or		LSB
iviode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0
Α	A1	A2				0	0	0	0	0
В	B1	B2				0	0	0	0	1
С	C1	C2		0		0	0	0	1	0
D single	DP1	DP2				0	0	0 0		1
E1 single	EP1	EN1	E. 11 4:44			0	1	0	1	0
E2 single	EN2	EP2	Full-diff		0	0	1	0	1	1
A diff	A1	B1	bias type select			0	1	1	1	1
C diff	B2	C2	Select			1	0	0	0	0
D diff	DP1	DP2				0	0	1	1	0
E full diff	EP1	EP2				0	1	0	0	0
Inp	ut SHORT				•	0	1	0	0	1
Prohibition							Other setting	)		

Input SHORT : The input impedance of each input terminal is lowered from  $100k\Omega(Typ)$  to  $6 k\Omega(Typ)$ . (For quick charge of coupling capacitor)

Mode	MSB Full-diff Bias Type Select							
	D7	D6	D5	D4	D3	D2	D1	D0
Negative Input	0	0	0	Input Selector				
Bias	1	U U Input Selector						

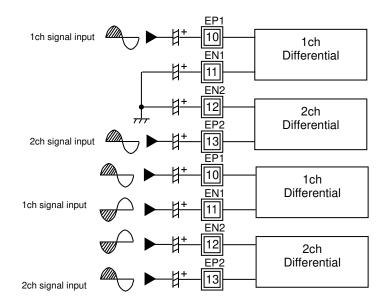
: Initial condition

Negative input type

For Ground –isolation type)

Bias type

For differential amplifier type



Select address 06 (hex)

Gain	MSB			Input	Gain			LSB
Gaiii	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Mute	0	0	0	1	0	1	1
12dB	ON/OFF	U	U	0	1	1	0	0
13dB				0	1	1	0	1
14dB			0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	1	0			
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB			1	0	0	0	1	
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
			1	1	0	1	1	
Prohibition				:	:	:	÷	:
				1	1	1	1	1

Mode	MSB		Mute ON/OFF LS						
Iviode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	0			Innut Cain			
ON	1	U	0			Input Gain			

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	ol, Fad	er Gai	n / Atte	enuatio	on	LSB
Gaill & All	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:		:	÷	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 41(hex)

Q factor	MSB		Bass Q factor LS					LSB
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0	0	Pac	ss fo	_	0	0	1
1.5	U	U	Das	55 10			1	0
2.0							1	1

fo	MSB			Bass	fo			LSB
TO	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz	_	0	0	1	1	0	В	ass actor
100Hz		0	1	0	]	U	Q fa	actor
120Hz			1	1	1			

Select address 44(hex)

Q factor	MSB		Middle Q factor				LSB		
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0	
0.75							0	0	
1.0	0	0	Mida	dle fo		_	0	1	
1.25	U	U	iviido	ile io	0	U	1	0	
1.5							1	1	

fo	MSB	ı		Middle	LSB			
10	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz		0	0	1	1 ,		Mic	ddle actor
1.5kHz	] 0	U	1	0	] 0	0	Q fa	actor
2.5kHz			1	1				

Select address 47 (hex)

Q factor	MSB		Tre	Treble (		Q factor		LSB
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Trob	ole fo	0	0	0	0
1.25	] 0	U	rrec	ne io	U	U	U	1

fo	MSB			Treble	e fo			LSB
10	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz			0	0				
10kHz	_	0	0	1	0	0	0	Treble Q factor
12.5kHz	] "	0	1	0	0	U	0	Q factor
15kHz			1	1				

Select address 51, 54, 57 (hex)

Select address 51, 54, 57 (hex)								
Gain	MSB	E	Bass/N	1iddle/	Treble	Gain		LSB
daiii	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost			0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
1 101110111011				1	1	1	1	0
				1	1	1	1	1

Mode	MSB	Bas	ss/Mid	dle/Tre	eble Bo	oost/C	ut	LSB
iviode	D7	D6	D5	D4	D3	D2	D1	D0
Boost	0	0	0		Page/	Middle/Treble	o Coin	
Cut	1	U	U		Dass	wildale/ Hebit	e Gaiii	

Select address 75 (hex)

	,								
Mode	MSB	·	Loudness Hicut         LSI           D5         D4         D3         D2         D1         D0           0					LSB	
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
Hicut1		0	0						
Hicut2	0	0	1	Loudness Gain					
Hicut3	U	1	0						
Hicut4		1	1						

Gain	MSB	MSB Lo			oudness Gain			
Gaill	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB		Loudness Hicut		0	1	0	1	0
11dB				0	1	0	1	1
12dB	0		udness Hicut	0	1	1	0	0
13dB					0	1	1	0
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

: Initial Condition

### (6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. Also, please turn ON MUTE at the set side until initial data is sent.

addition at adphy voltage on vites, please tain out the vet old artifulation and									
Parameter	Symbol	Limit			Unit	Conditions			
Parameter		Min	Тур	Max	Offic	Conditions			
Rise Time of VCC	trise	33	-	-	μsec	V <sub>CC</sub> rise time from 0V to 5V			
VCC Voltage of Release Power ON Reset	V <sub>POR</sub>	-	4.1	-	V				

# (7) About External Compulsory Mute Terminal

It is possible to forcibly set Mute from the outside by setting input voltage at the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

# **Application Information**

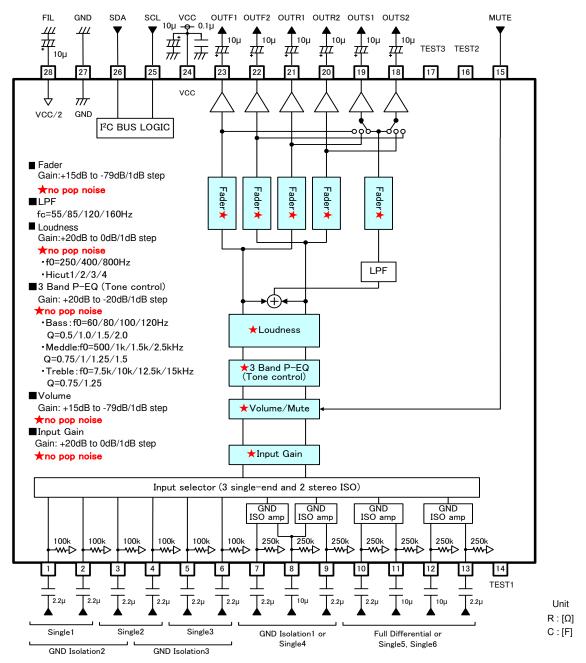
# 1. Function and Specifications

Function	Specifications							
	· (Stereo input)							
	· Single-End/Diff/Full-Diff							
	(Possible to set the number of single-end/diff/full-diff as follows)							
	Single-End Differential Full-Differential							
Input	Mode 1	0	3	1				
selector	Mode 2 Mode 3	<u> </u>	<u>2</u> 1	1				
	Mode 4	4	0	1				
	Mode 5	5	1	0				
	Mode 6	6	0	0				
	00 ID 1		ombination of inp	out selector				
Input		0dB (1dB step)						
gain	Possible	to use "Advanc	ed switch" for pre	evention of switching no	oise.			
Mute	Possible	to use "Advance	ed switch" for pre	evention of switching no	oise.			
Volume	· +15dB to	-79dB (1dB ste	p), -∞dB					
	· Possible	to use "Advance	ed switch" for pre	evention of switching no	oise.			
	· +20dB to -20dB (1dB step)							
Bass	· Q=0.5, 1, 1.5, 2							
5400	· fo=60, 80, 100, 120Hz							
	Possible to use "Advanced switch" when changing gain							
	· +20dB to -20dB (1dB step)							
Middle	· Q=0.75, 1, 1.25, 1.5							
Wildale	· fo=500, 1k, 1.5k 2.5kHz							
	Possible to use "Advanced switch" when changing gain							
	· +20dB to	-20dB (1dB ste	ep)					
Treble	· Q=0.75, 1.25							
110010	· fo=7.5k, 10k, 12.5k, 15kHz							
	· Possible	to use "Advanc	ed switch" when	changing gain				
Fader	· +15dB to -79dB(1dB step), -∞dB							
1 addi	· Possible	to use "Advanc	ed switch" for pre	evention of switching no	oise.			
	· +20dB to	0dB(1dB step)						
Loudness	· fo=250/40	00/800Hz						
	· Possible	to use "Advanc	ed switch" for pre	evention of switching no	oise.			
LPF	· fc=55/85/120/160Hz, pass							
Er I	· Phase shift (0°/180°)							

# 2. Volume / Fader Volume Attenuation Data

(dB) D7 D6 D5 D4 D3 D2 D1 D	0 / JD\	D-7		_					
	0 (dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15 0 1 1 1 0 0 0	-33	1	0	1	0	0	0	0	1
+14 0 1 1 1 0 0 1 (		1	0	1	0	0	0	1	0
+13 0 1 1 1 0 0 1		1	0	1	0	0	0	1	1
+12 0 1 1 1 0 1 0		1	0	1	0	0	1	0	0
+11 0 1 1 0 1 0		1	0	1	0	0	1	0	1
+10 0 1 1 1 0 1 1		1	0	1	0	0	1	1	0
+9 0 1 1 1 0 1 1		1	0	1	0	0	1	1	1
+8 0 1 1 1 1 0 0		1	0	1	0	1	0	0	0
+7 0 1 1 1 1 0 0		1	0	1	0	1	0	0	1
+6 0 1 1 1 1 0 1		1	0	1	0	1	0	1	0
+5 0 1 1 1 1 0 1		1	0	1	0	1	0	1	1
+4 0 1 1 1 1 0 0		1	0	1	0	1	1	0	0
+3 0 1 1 1 1 0		1	0	1	0	1	1	0	1
+2 0 1 1 1 1 1 0		1	0	1	0	1	1	1	0
+1 0 1 1 1 1 1 1		1	0	1	0	1	1	1	1
0 1 0 0 0 0 0 0		1	0	1	1	0	0	0	0
-1 1 0 0 0 0 0 0		1	0	1	1	0	0	0	1
-2 1 0 0 0 0 0 0		1	0	1	1	0	0	1	0
-3 1 0 0 0 0 0 1		1	0	1	1	0	0	1	1
-4 1 0 0 0 0 1 0 0		1	0	1	1	0	1	0	0
		1	0	1	1	0	1	0	1
		1	0			_	1	1	
		1	0	1	1	0	1	<del></del>	1
-7   1   0   0   0   0   1   1   1   1   1		1	0	1	1	0	0	0	0
		1	0	1	1	1	0	0	1
-9 1 0 0 0 1 0 0 1 0 1 0 1 0 1 0 1 0 1 0		1	0	1	1	1	0	1	0
			0	1		1		-	
		1	0	1	1	1	0	1	0
			_		1	1	1	0	
		1	0	1				1	1
-14		1	0	1	1	1	1	1	0
		1	1	0	0	0	0	0	0
									_
-17		1	1	0	0	0	0	1	0
		1	1	0	0	_		1	1
<del>                                     </del>		1	1	_	0	0	1	0	_
			<u> </u>	0	_			0	0
		1	1	_	0	0	1	-	1
		1	1	0	0	0	1	1	0
-23		1		0	0	0	1	1	1
	_	1	1	0		1	0	0	0
			<u> </u>	0	0		0	0	
-26   1   0   0   1   1   0   1   0		1	1	0	0	1	0	1	0
-27   1   0   0   1   1   0   1		1	1	0	0	1	0	1	1
-28 1 0 0 1 1 1 0 0		1	1	0	0	1	1	0	0
-29 1 0 0 1 1 1 0		1	1	0	0	1	1	0	1
-30 1 0 0 1 1 1 1 (		1	1	0	0	1	1	1	0
-31 1 0 0 1 1 1 1 1		1	1	0	0	1	1	1	1
-32   1   0   1   0   0   0   0	-∞	1	1	1	1	1	1	1	1

#### 3. Application Circuit



(Note) About single input 1 to 3, it is possible to change from single input to GND Isolation input 2.3. (Note) About GND Isolation1 and Full Differential, it is possible to change from differential input to single input 4 to 6.

### Notes on wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- ② GND lines should be one-point connected.
- ③ Wiring pattern of Digital shall be away from that of analog unit and crosstalk should not be acceptable.
- 4 If possible, SCL and SDA lines of I<sup>2</sup>C BUS should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 5 If possible, analog input lines should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 6 TEST pins (Pin 14,15,16) should be OPEN.

## **Power Dissipation**

About the thermal design of the IC

Characteristics of an IC are greatly affected by the temperature at which it is used. Exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

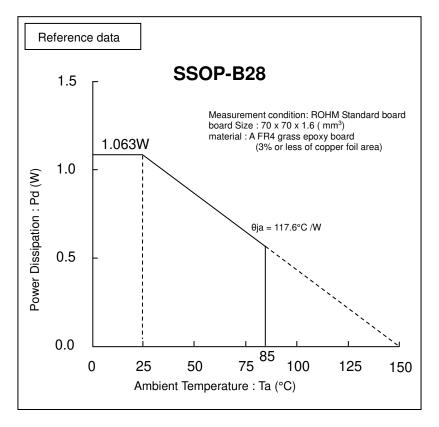


Figure 23. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Equivalent Circuits									
Terminal	Terminal	Terminal	Equivalent Circuit	Terminal Description					
No.	Name	Voltage	•						
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25	VCC VB VB VB VB VB VB	A terminal for signal input. The input impedance is $100k\Omega$ (Typ).					
7 8 9 10 11 12 13	DP1 DN DP2 EP1 EN1 EN2 EP2	4.25	VCC VCC VCC VCC VCC VCC VCC VCC	Input terminal available to single/Differential mode. The input impedance is 250kΩ (Typ).					
15	MUTE	-	VCC Z BV BV 1.65V	A terminal for external compulsory mute. If terminal voltage is High level, the mute is OFF. And if the terminal voltage is Low level, the mute is ON.					
18 19 20 21 22 23	OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC D	A terminal for fader and Subwoofer output.					

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

# I/O Equivalent Circuits - continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
24	VCC	8.5		Power supply terminal.
25	SCL	-	VCC O 1.65V	A terminal for clock input of I <sup>2</sup> C BUS communication.
26	SDA	-	VCC O J J J J J J J J J J J J J J J J J J	A terminal for data input of I <sup>2</sup> C BUS communication.
27	GND	0		Ground terminal.
28	FIL	4.25	VCC	Voltage for reference bias of analog signal system. The simple pre-charge circuit and simple discharge circuit for an external capacitor are built in.
14 16 17	TEST	-		TEST terminal

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

#### **Operational Notes**

#### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

#### 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

### 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

#### 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

#### 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

#### 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

#### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

#### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

# 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

### 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

### 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

#### Operational Notes - continued

#### 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

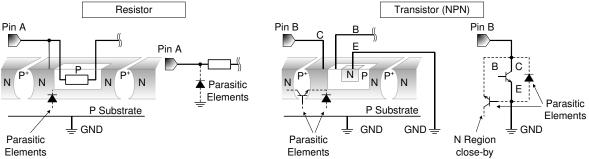
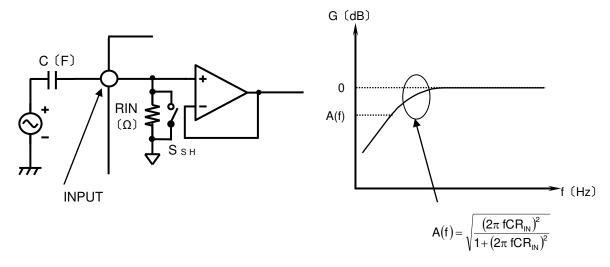


Figure 24. Example of monolithic IC structure

### 13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value The constant value of input coupling capacitor C(F) is decided with respect to the input impedance R<sub>IN</sub>(Ω) at the input signal terminal of the IC that would be sufficient to form an RC characterized HPF.



(b) About the Input Selector SHORT SHORT mode is the command which makes switch S<sub>SH</sub> =ON of input selector part so that the input impedance R<sub>IN</sub> of all terminals becomes small. Switch S<sub>SH</sub> is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S<sub>SH</sub> and makes it low impedance, please use it at no signal condition.

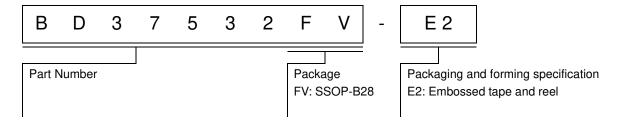
#### 14. About Mute Terminal (Pin 15) when Power Supply is OFF

There should be no applied voltage to Mute terminal (Pin 15) when power-supply is OFF. If in case voltage is supplied to Mute terminal, please insert a series resistor (about  $2.2k\Omega$ ) to Mute terminal. (Please refer to Application Circuit Diagram.)

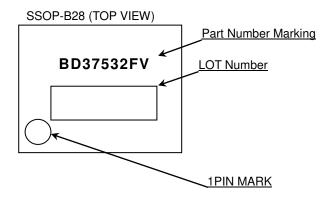
### 15. About TEST Pin

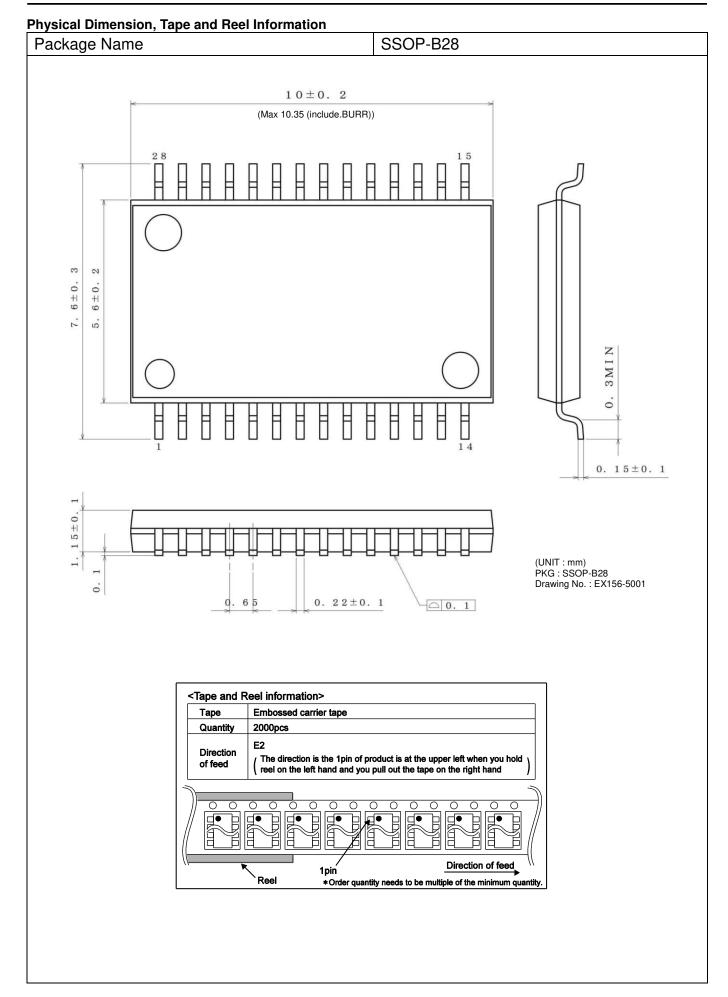
TEST Pin should be OPEN. Pin 14. 16, 17 are TEST Pins

# **Ordering Information**



# **Marking Diagram**





# **Revision History**

Date	Revision	Changes
16.Dec.2015	001	New Release

# **Notice**

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Ī	JÁPAN	USA	EU	CHINA
Ī	CLASSⅢ	CLACCIII	CLASS II b	CL ACCIII
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  - [h] Use of the Products in places subject to dew condensation
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For details, please refer to ROHM Mounting specification

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
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